

Tracewell T-FX2he

BASED ON: The Dell EMC PowerEdge FX architecture. Converged platform houses flexible blocks of server, storage and I/O resources while providing efficiency through shared power, networking and management.

USE CASE: Ideal for customers that require enterprise-class compute capabilities but need a compact form factor, enhanced storage options and the ability to support mobile applications in a rugged, "roll aboard" transit case. .



8.4"H x 9.2"W x 24.5"D

FORM FACTOR HIGHLIGHTS:

Enterprise class hardware in a highly compact form factor engineered to deliver extremely portable, rugged computing.

The Tracewell Extended Storage Module (ESM) further enhances system capabilities by adding up to (8) 2.5" drives to each T-FX2he platform.

Benefits

DELL TECHNOLOGIES

Enterprise-class modular infrastructure that combines the density and efficiency of blades with the simplicity and cost benefits of rack systems. Flexible and customizable servers, storage and networking.

TRACEWELL PLATFORMS

Features Dell EMC FX architecture in a form factor that is half the width of a standard Dell EMC FX product. Offers extended storage capabilities in a highly compact chassis or shock and vibe isolated, rugged transit case.

DELL TECHNOLOGIES +TRACEWELL

Electrically identical to standard Dell EMC products. "Plug and play" components between Dell EMC products and Tracewell platforms. Order through Dell EMC (Dell EMC part number) and eligible for Dell EMC warranty, service, support and secure supply chain.

The Tracewell T-FX2he Specifications Summary

The Tracewell T-FX2he accepts standard Dell hardware configurations.

STANDARD DELL EMC PRODUCT CONFIGURATIONS

PROCESSOR TYPE	Quarter-Width (QW): Intel® Xeon® E5-2600 v4 family of processors, up to 18 cores per processor (1 or 2 processors).
	Half-Width (HW): Intel® 2nd generation Xeon® Scalable processors, up to 28 cores per processor (1 or 2 processors).
MEMORY ARCHITECTURE	QW: 8 DDR4 slots, supports 2133MT/s LRDIMM and RDIMM, 512GB Max DDR4.
	HW: 16 DDR4 DIMM slots, supports RDIMM / LRDIMM, up to 2933MT/s speeds, 2TB Max DDR4.
RAID CONTROLLER	Hardware RAID, Levels 0, 1, 5, 10 or pass through.
STORAGE	Processing Sleds: QW: Up to two 1.8" or 2.5" drives.
	HW: Up to ten 2.5" drives with Extended Storage Module (ESM), up to 6 drives with Extended Storage Module PCIe (ESMP), SAS/SATA/*NVMe, SSD/HDD.
	Standard FC640* with onboard SATA to PCH, 1 or 2 drives. Optional ESM with PERC RAID controller, up to 8 drives. Internal SD vFlash site. Optional internal USB and dual SD sites (hypervisor).
	* Lower FC640 can be equipped with one ESM, ESMP, or ESM filler panel. Up to (2) NVMe front drives.
VIDEO	G200 (integrated with iDRAC). FC430: 16MB, FC640: 4GB. Video memory shared with iDRAC application memory.
SLED SLOTS	Sled bay supports up to four (QW), or two (HW) processing sleds and up to 1 Extended Storage Module (ESM). Accepts standard FC640 processing sled with appropriate configuration or filler panels.
	(4) FC430; (1) FC640 and (1) FC640 with ESM/P or filler; or (2) FC430 & (1) FC640 with ESM/P or filler.
I/O MODULES	Ethernet: Supports up to 2 I/O aggregator modules. Modules are available in pass-through and switching configurations.
PCIe	Up to (1) x16 PCle Gen3 LP card or (2) x8 PCle Gen3 LP cards. SMART Card Reader. Requires ESMP option.
CHASSIS Management Controller	Single, dual-port chassis management module. Two dedicated 10/100/1000Mb RJ45 ports: One for external management network, one for daisy chaining or NIC failover. Serial 9-pin, DTE, 16550 compatible.
FRONT ACCESSIBLE I/O	One USB 2.0 connector for keyboard and mouse support. One additional USB 2.0 connector. One 15-pin VGA video connector. KVM selector switch. On / Standby switch.

POWER SUPPLY	Up to two power supplies supported. Available in 2400W / 2000W / 1600W output (per PS). N+1 capable.
	High-line operation up to 2400W with N+1 redundancy or 3000W* non-redundant.
	Low-line operation up to 1400W with N+1 redundancy or 2800W* non-redundant.
	Input voltage: 90-264 VAC.
	Maximum inrush current: 25A (35A; 2400W).
	* CMC system limits power usage within the system architecture.
COOLING AND ENVIRONMENTAL	Rear removable fan module with high-pressure fans. Normal Operating Temp: 10°C to 35°C (50°F to 95°F).
	Expanded Operating Temp: -5°C to 45°C (23°F to 113°F) with some restrictions.
	Storage Temp: -40°C to 65°C (-40°F to 149°F).
	EMC: Enterprise class FCC emissions.

TRACEWELL SYSTEMS PRODUCT CONFIGURATIONS

CHASSIS	Bonded aluminum low-mass chassis for rigidity with minimum weight.
	Front and rear mounting points to allow hard mounting. Additional mounting locations for sled lock bars. Retractable side handles included. Optional: Rack mounting flanges, removable front guard with particle filter, line cord retainer kit and processing sleds.
TRANSIT CASE	OPTIONAL: Integrated rugged transit case, shock isolated, overall size 29.8" D x 13.2" W x 13.2" H Retractable Handles, Removable front and rear panels, stackable.
DIMENSIONS	9.2"W x 8.4"H x 24.5"D.

For more information, see the Tracewell T-FX2he Data Sheet.

ABOUT TRACEWELL SYSTEMS

For more than 40 years Tracewell has enabled the nation's largest military and commercial organizations to deliver powerful and reliable computing solutions in environments where size, weight, power and other constraints present challenges that cannot be met by standard computing systems. Tracewell Systems have been recognized by the top names in the defense and technology sectors for their commitment to Trusted Innovation – a process where the company solves previously impossible, sensitive, mission-critical platform challenges through customer solution design, engineering and manufacturing, all under one roof. More information: www.tracewell.com.

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